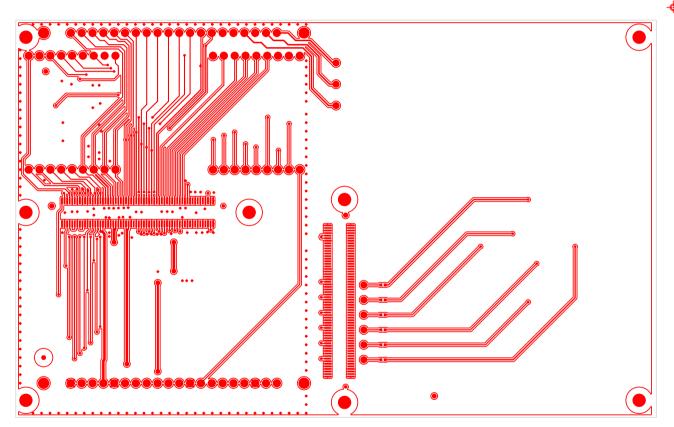


ADuCM350 Display-CapTouch Board (Rev-B) - Component Side View

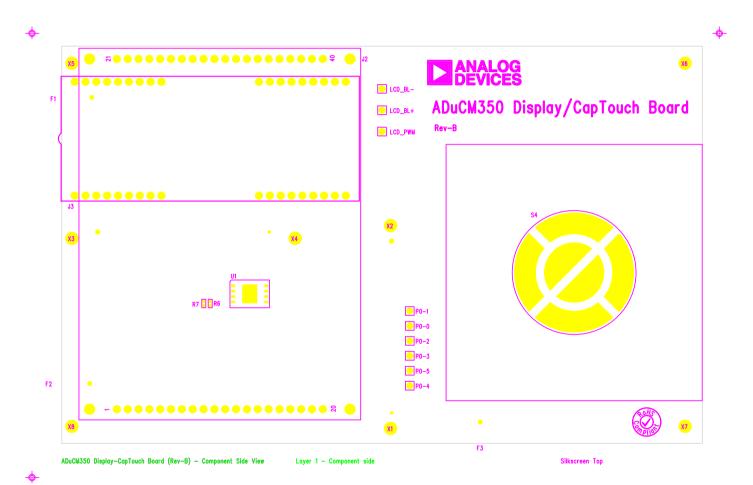
Layer 1 - Component side

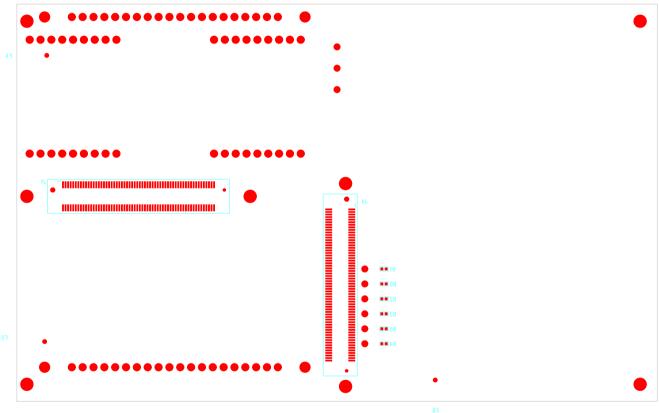




ADuCM350 Display-CapTouch Board (Rev-B) - Component Side View

Layer 2 - Solder Side

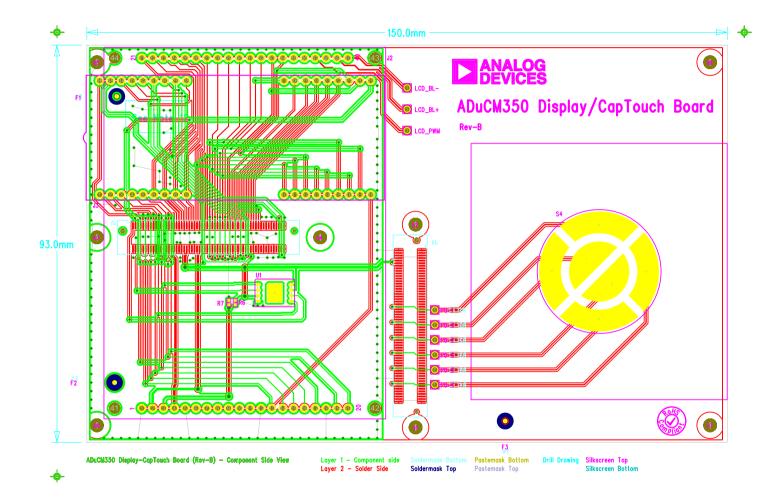




ADuCM350 Display-CapTouch Board (Rev-B) - Component Side View

Layer 2 - Solder Side

Silkscreen Bottom





- Ploted thru holes and the conductive pattern electroplated with 0.001' min. thick copper. Terminal areas and plated thru holes to be ENIG plated. Soldermask over bare copper.

 3. Finished Board to be RoHS Compliant

 4. Datum for (x,y) co-ordinate drill files at LLH corner.

- 5. Processing tolerances:
- A. Conductive pattern front to back registration within .005' total.
 B. Minimum annular ring surrounding holes: 0.002'
 C. Finished conductive pattern within .002' of true size.
 6. Warp and twist within .010 inch per inch

- Warp and twist within .010 inch per inch
 Dimensions are for the finished part.
 Solder Mask: Liquid photo imagable solder mask over bare copper (smobc), colour green, both sides using the patterns provided. No mask is permitted on the terminal areas. Soldermask to etch registration within .005' total.
 Screening: Screen component outlines and nomenclature using indelible white ink on the primary and secondary sides (as required). Nomenclature shall be legible. Screen to etch registration within .020' total.
 Surfaces: Punched or machined surfaces 125 micro inches rms max.
 Break all sharp edges .015' R max.
 Manufacturers ident, UL number & date code (YY/WW format) must be added in this area on the silkscreen